1. Part No. Expression

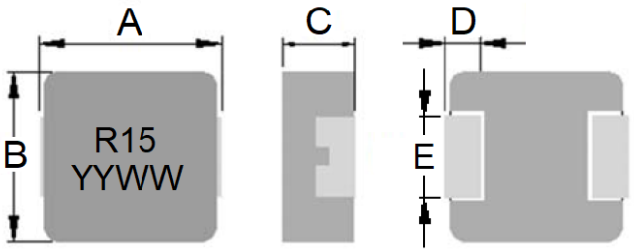
P I C Q 1 0 0 4 H R 1 5 Y F

(a) (b) (c) (d) (e) (f)

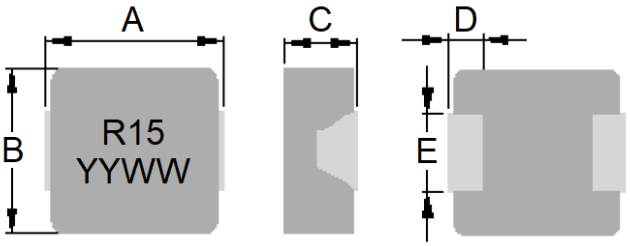
(a)	Series Code	(d)	Inductance Code
(b)	Dimension Code	(e)	Tolerance Code
(c)	Material Code	(f)	Packaging Code

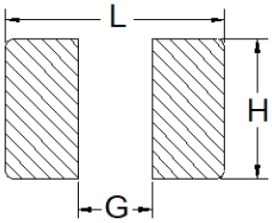
2. Configuration & Dimensions (Unit: mm)

leadframe



non-leadframe





Recommended PCB Layout

Note: 1. The above PCB layout reference only.

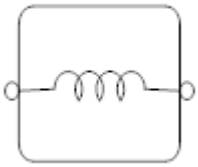
2. Recommend solder paste thickness at 0.15 mm and above.

3. Marking: Top= Inductance Code, Bottom=YYWW (Year/World week), Black

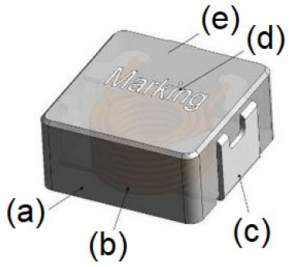
Type	A	B	C	D	E	L	G	H
Leadframe	11.0±0.5	10.0±0.3	3.8±0.2	2.3±0.3	3.0±0.3	13.6 Ref	5.4 Ref	3.5 Ref
Non-Leadframe								

NOTE: Specifications subject to change without notice. Please check our website for latest information.

3. Schematic

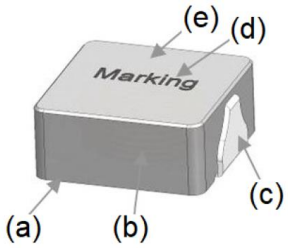


4. Material List



Lead Frame

NO	Items
(a)	Core
(b)	Wire
(c)	Clip
(d)	Ink
(e)	Paint



Non-Lead Frame

NO	Items
(a)	Core
(b)	Wire
(c)	Solder
(d)	Ink
(e)	Paint

5. General Specifications

(a) Reliability test for this part meets AEC-Q200 standard.

(b) Operating Temp.: - 55°C to + 125°C (including self-temperature rise)

(c) Storage Temp.: - 55°C to + 125°C (on board)

(d) All test data referenced to 25°C ambient.

(e) Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40°C.

(f) Saturation Current (Isat) will cause inductance L0 to drop approximately 30%.

(g) Rated DC Current: The lower value of Irms and Isat.

(h) Part Temperature (Ambient + Temp. Rise): Should not exceed 125°C under worst case operating conditions.

(i) Maximum Operating Voltage: 75V

(j) Storage Condition (Component in its packaging)

i) Temperature: Less than 40°C

ii) Humidity: Less than 60% RH

NOTE: Specifications subject to change without notice. Please check our website for latest information.

6. Electrical Characteristics

Part Number	Inductance (μH) @0A	Irms (A) Typ	Isat (A) Typ	DCR (mΩ)		Type
				Typ	Max	
PICQ1004HR15YF	0.15	43.0	75.0	0.5	0.6	Non-Leadframe
PICQ1004HR19YF	0.19	36.0	70.0	0.6	0.9	Non-Leadframe
PICQ1004HR20YF	0.20	35.0	70.0	0.66	0.95	Non-Leadframe
PICQ1004HR22MF	0.22	35.0	60.0	0.8	1.0	Non-Leadframe
PICQ1004HR24MF	0.24	34.0	60.0	0.8	1.0	Non-Leadframe
PICQ1004HR27MF	0.27	33.0	60.0	0.82	1.0	Non-Leadframe
PICQ1004HR30MF	0.30	32.0	60.0	0.94	1.1	Non-Leadframe
PICQ1004HR36MF	0.36	31.0	60.0	1.05	1.2	Non-Leadframe
PICQ1004HR39MF	0.39	30.0	60.0	1.1	1.3	Non-Leadframe
PICQ1004HR45MF	0.45	29.0	45.0	1.3	1.5	Non-Leadframe
PICQ1004HR47MF	0.47	28.0	43.0	1.3	1.5	Non-Leadframe
PICQ1004HR56MF	0.56	25.0	40.0	1.6	1.8	Non-Leadframe
PICQ1004HR68MF	0.68	22.0	39.0	2.4	2.7	Non-Leadframe
PICQ1004HR75MF	0.75	22.0	39.0	2.4	2.7	Non-Leadframe
PICQ1004HR88MF	0.88	20.0	38.0	2.5	2.9	Non-Leadframe
PICQ1004H1R0MF	1.00	18.0	36.0	3.0	3.3	Non-Leadframe
PICQ1004H1R2MF	1.20	17.0	33.0	3.3	3.8	Non-Leadframe
PICQ1004H1R5MF	1.50	16.0	33.0	4.0	4.6	Non-Leadframe
PICQ1004H1R8MF	1.80	14.0	30.0	5.3	6.4	Leadframe
PICQ1004H2R2MF	2.20	12.0	27.0	6.5	7.0	Leadframe
PICQ1004H2R5MF	2.50	11.5	23.0	7.9	8.7	Leadframe
PICQ1004H3R0MF	3.00	11.5	21.0	10.0	11.5	Leadframe
PICQ1004H3R3MF	3.30	11.0	20.0	10.8	11.8	Leadframe
PICQ1004H3R9MF	3.90	10.5	19.0	12.6	14.5	Leadframe
PICQ1004H4R0MF	4.00	10.2	18.0	13.0	15.0	Leadframe
PICQ1004H4R7MF	4.70	10.0	17.0	15.0	15.5	Leadframe
PICQ1004H5R6MF	5.60	9.0	14.0	17.0	19.3	Leadframe

Tolerance Code: M =±20%, Y =±30%
Test frequency: 1.0V/100KHz

NOTE: Specifications subject to change without notice. Please check our website for latest information.

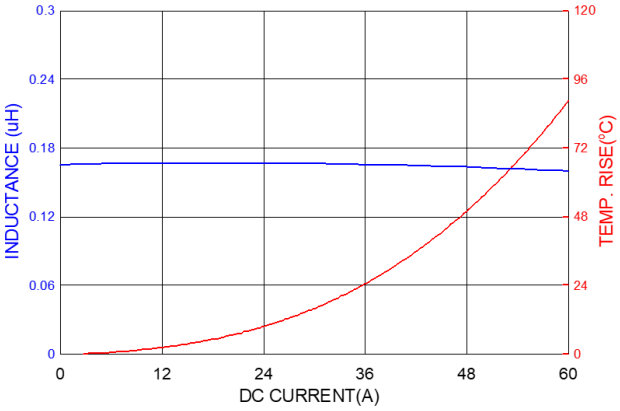
Part Number	Inductance (μH) @0A	Irms (A) Typ	Isat (A) Typ	DCR (mΩ)		Type
				Typ	Max	
PICQ1004H6R2MF	6.20	8.7	13.7	17.2	21.3	Leadframe
PICQ1004H6R5MF	6.50	8.6	13.6	17.3	22.3	Leadframe
PICQ1004H6R8MF	6.80	8.5	13.5	17.5	23.3	Leadframe
PICQ1004H7R3MF	7.30	8.3	13.0	19.0	21.8	Leadframe
PICQ1004H8R2MF	8.20	8.0	12.5	20.0	22.5	Leadframe
PICQ1004H100MF	10.0	7.5	12.0	27.0	30.0	Leadframe
PICQ1004H150MF	15.0	6.25	10.0	40.0	45.0	Leadframe
PICQ1004H180MF	18.0	5.5	9.0	56.0	62.0	Leadframe
PICQ1004H220MF	22.0	5.0	7.0	64.0	74.0	Leadframe
PICQ1004H270MF	27.0	4.0	6.0	86.0	100	Leadframe
PICQ1004H330MF	33.0	3.5	5.0	92.0	112	Leadframe
PICQ1004H470MF	47.0	3.0	4.5	145	167	Leadframe
PICQ1004H680MF	68.0	2.0	3.0	205	240	Leadframe
PICQ1004H820MF	82.0	1.5	2.5	265	320	Leadframe

Tolerance Code: M =±20%, Y =±30%
Test frequency: 1.0V/100KHz

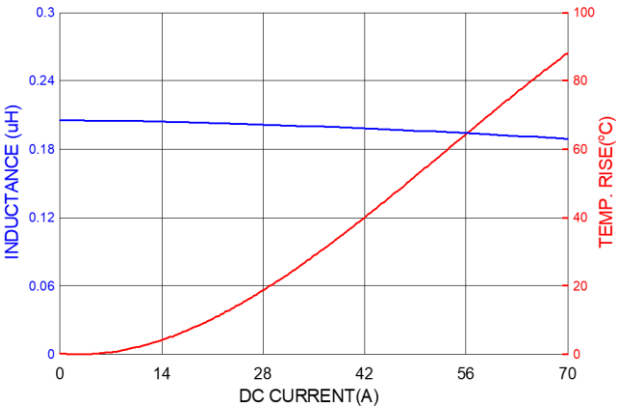
NOTE: Specifications subject to change without notice. Please check our website for latest information.

7. Characteristics Curve

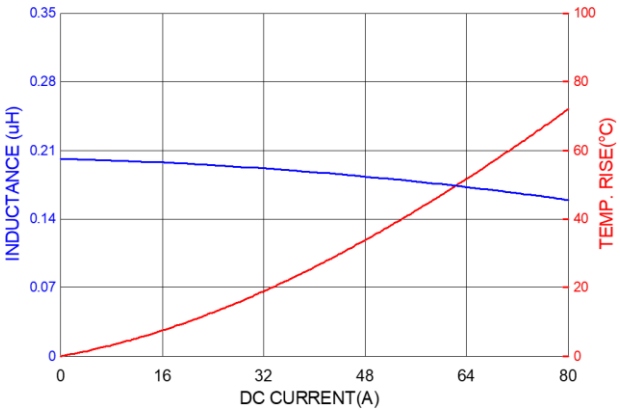
PICQ1004HR15YF



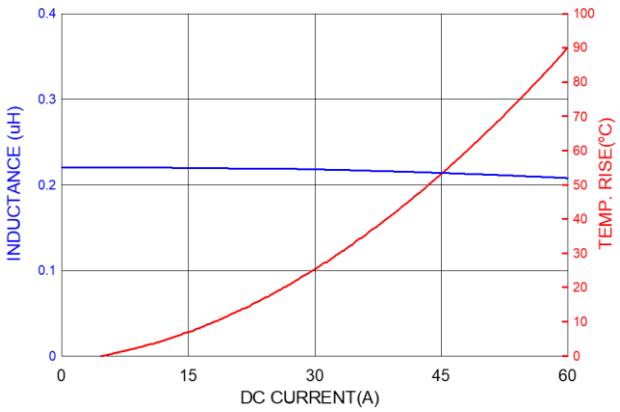
PICQ1004HR19YF



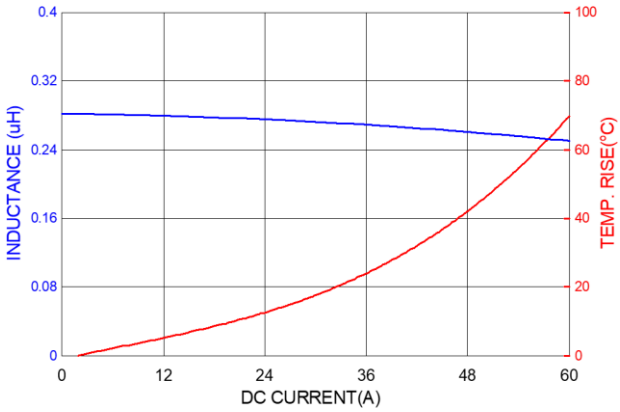
PICQ1004HR20YF



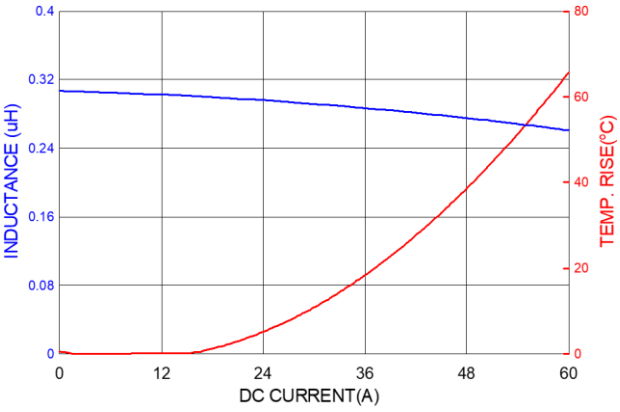
PICQ1004HR22MF



PICQ1004HR24MF

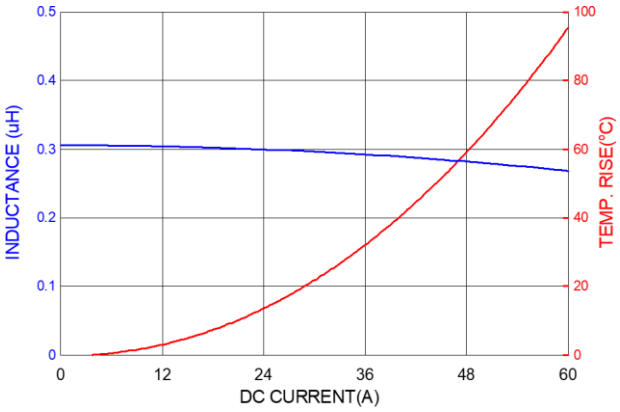


PICQ1004HR27MF

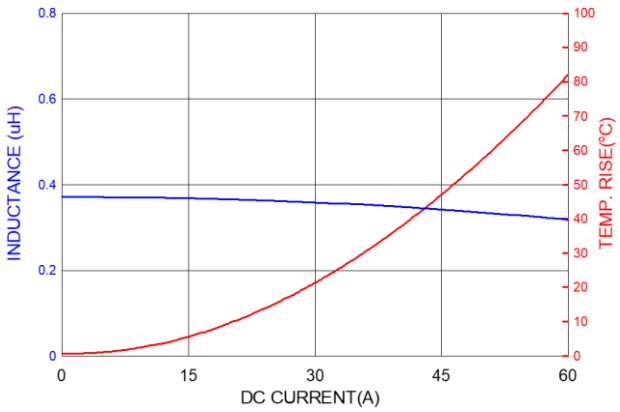


NOTE: Specifications subject to change without notice. Please check our website for latest information.

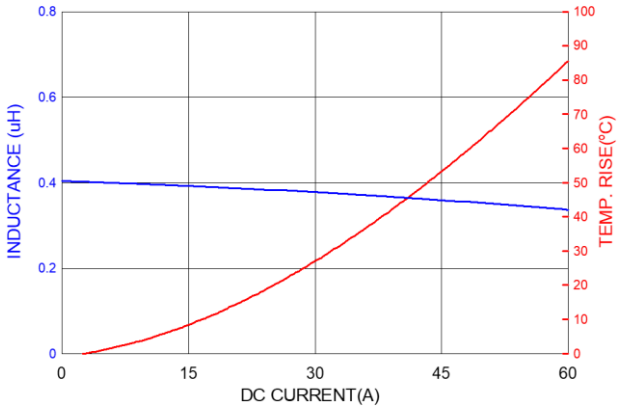
PICQ1004HR30MF



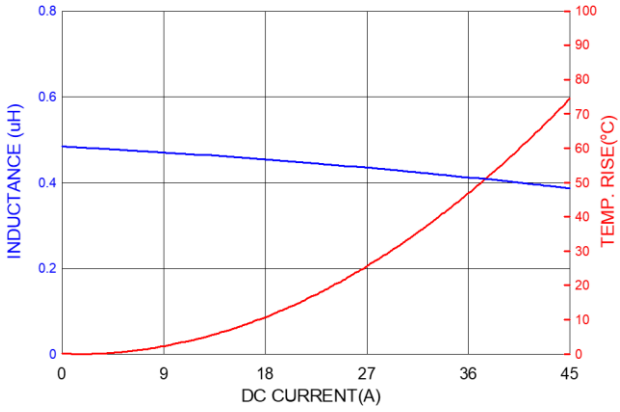
PICQ1004HR36MF



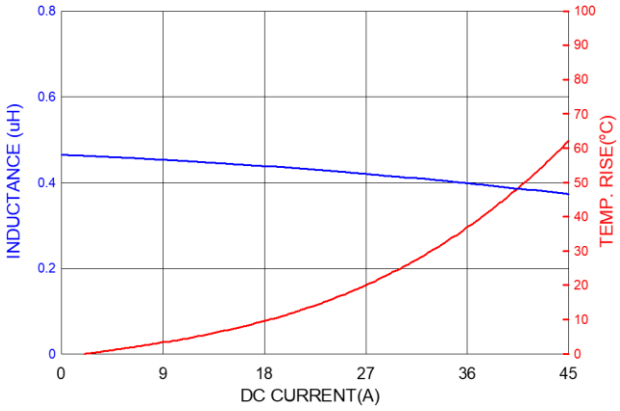
PICQ1004HR39MF



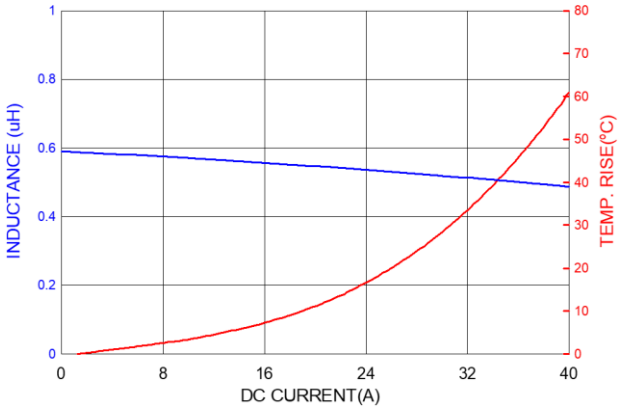
PICQ1004HR45MF



PICQ1004HR47MF

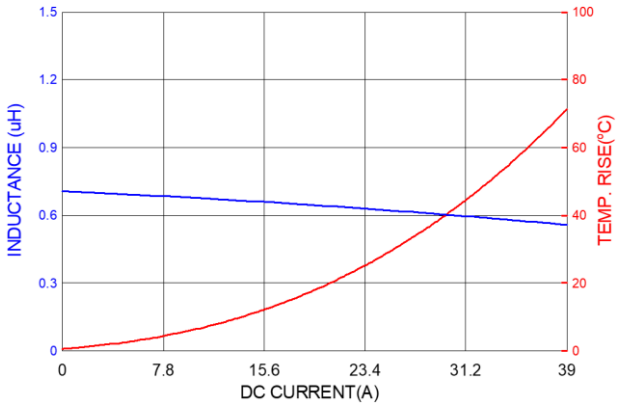


PICQ1004HR56MF

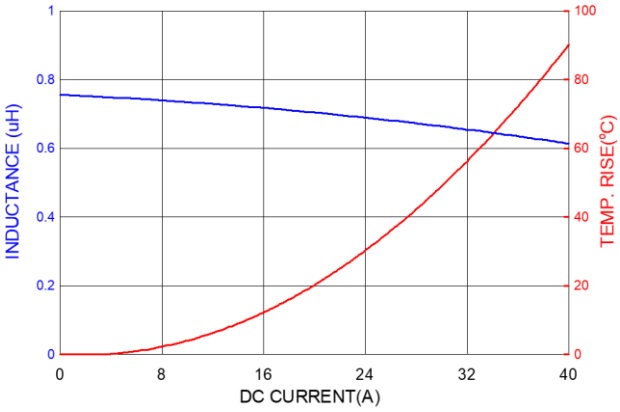


NOTE: Specifications subject to change without notice. Please check our website for latest information.

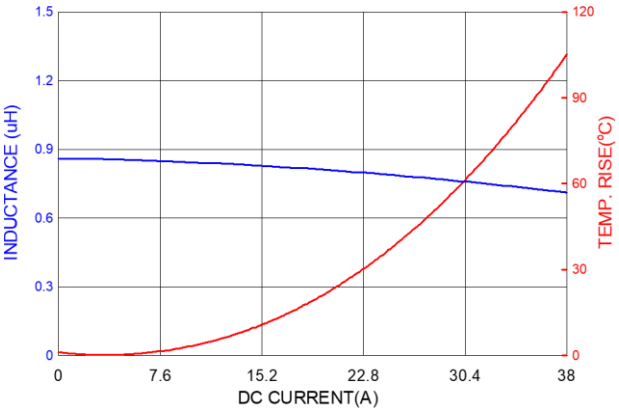
PICQ1004HR68MF



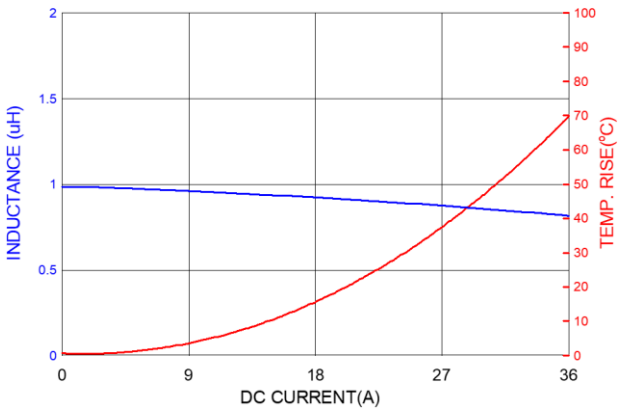
PICQ1004HR75MF



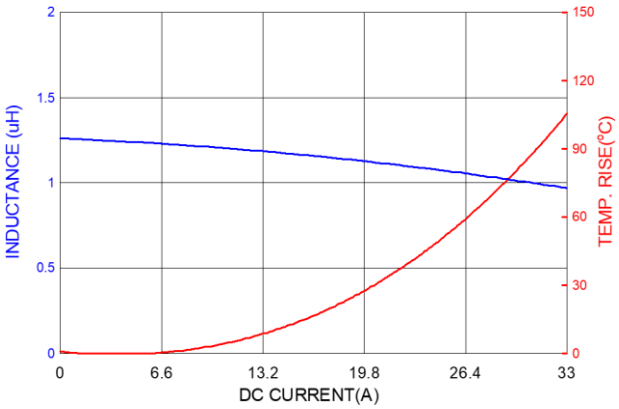
PICQ1004HR88MF



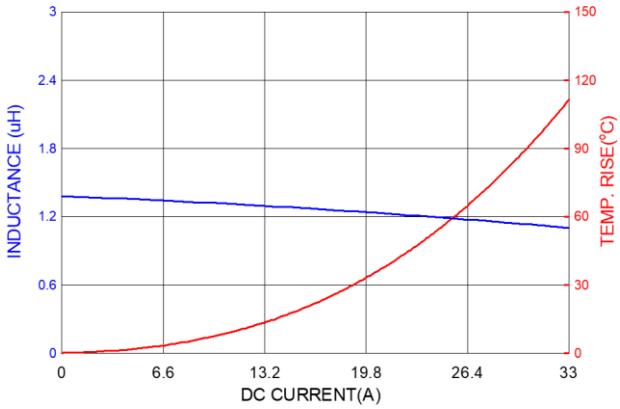
PICQ1004H1R0MF



PICQ1004H1R2MF

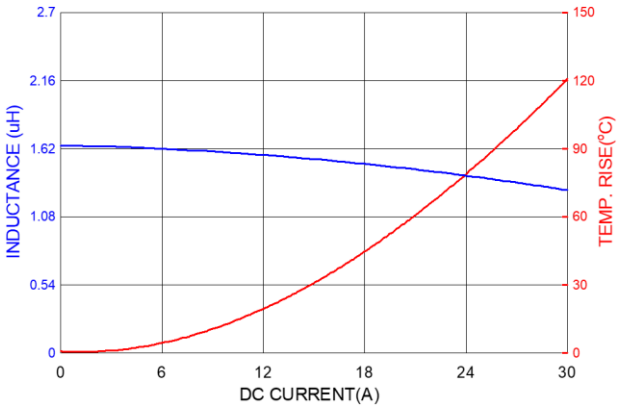


PICQ1004H1R5MF

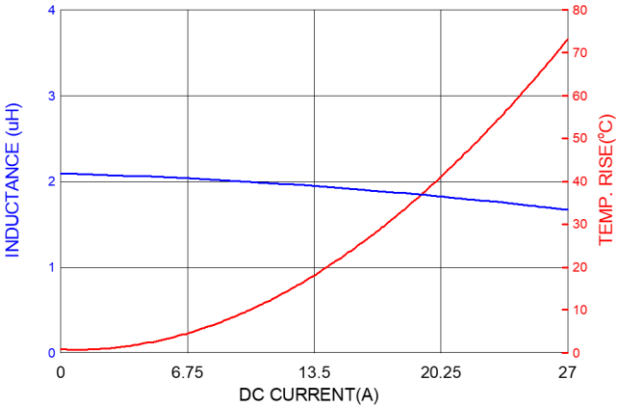


NOTE: Specifications subject to change without notice. Please check our website for latest information.

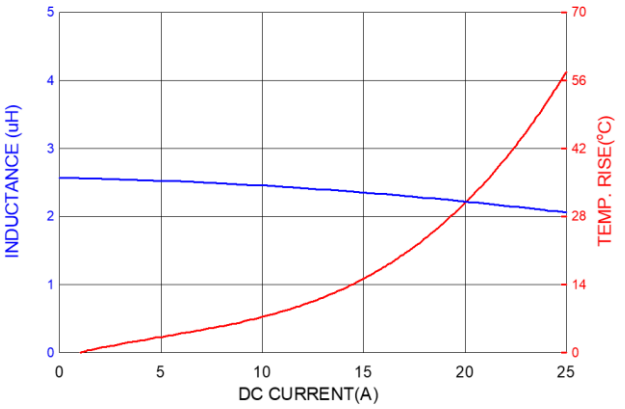
PICQ1004H1R8MF



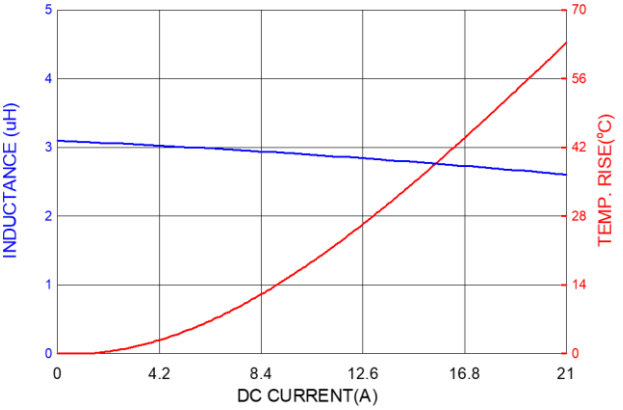
PICQ1004H2R2MF



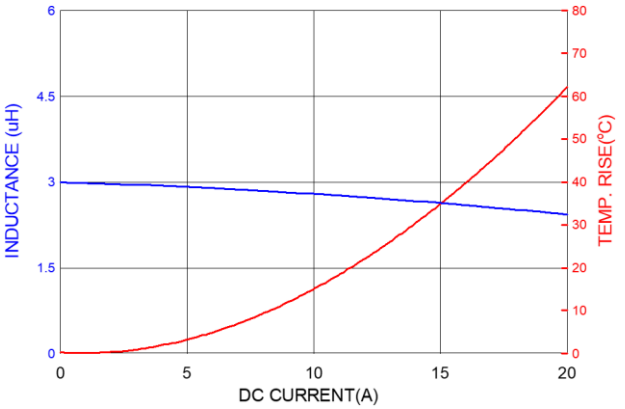
PICQ1004H2R5MF



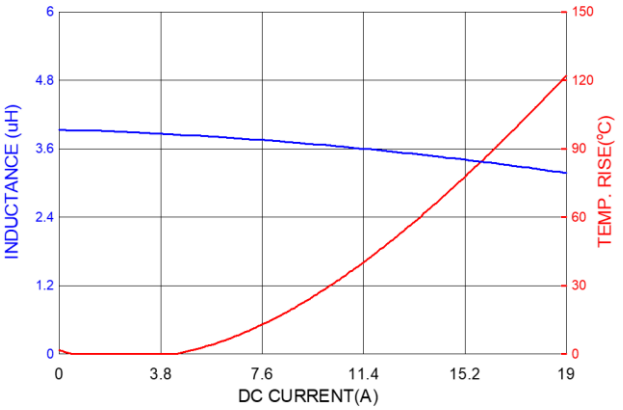
PICQ1004H3R0MF



PICQ1004H3R3MF

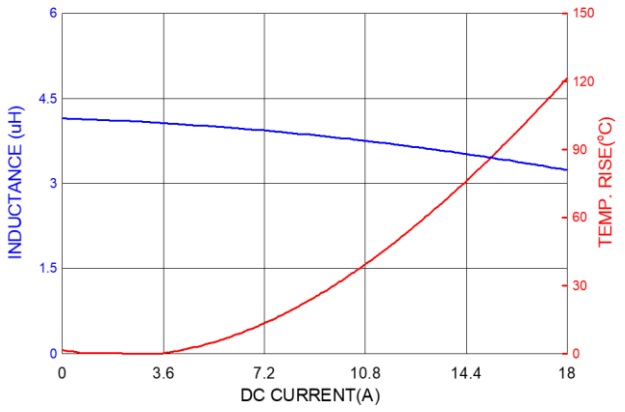


PICQ1004H3R9MF

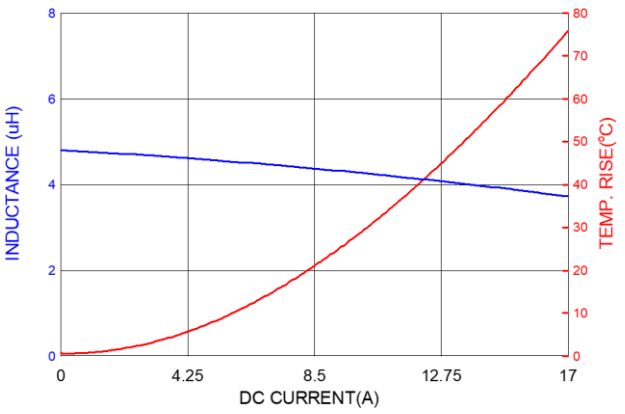


NOTE: Specifications subject to change without notice. Please check our website for latest information.

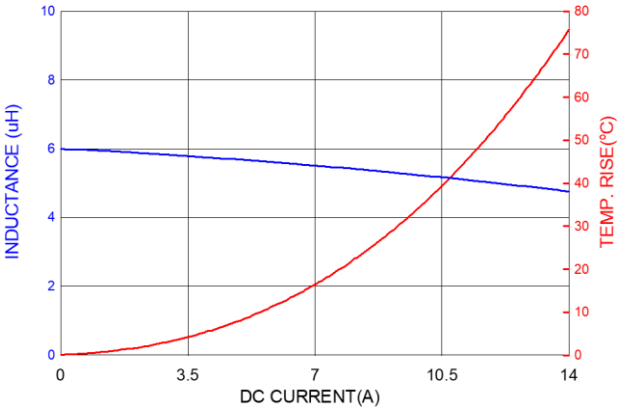
PICQ1004H4R0MF



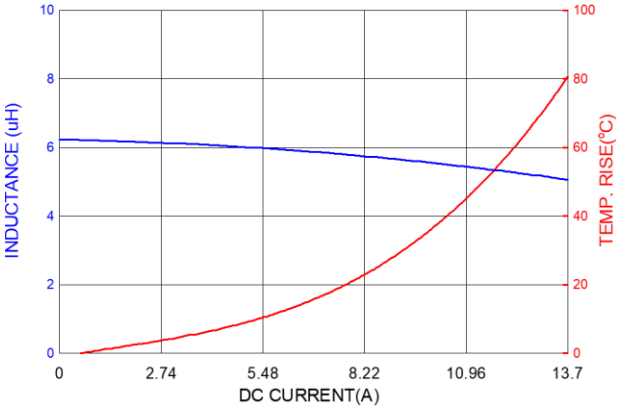
PICQ1004H4R7MF



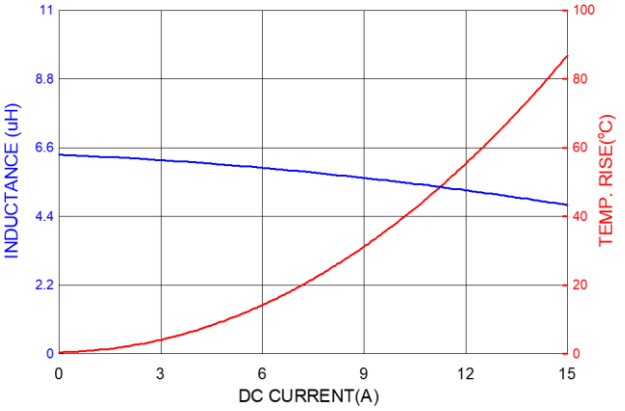
PICQ1004H5R6MF



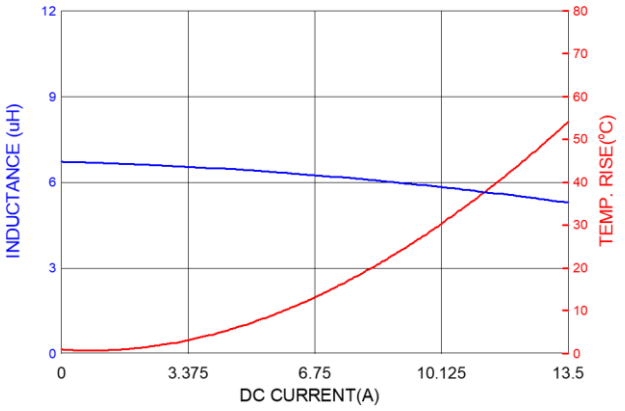
PICQ1004H6R2MF



PICQ1004H6R5MF

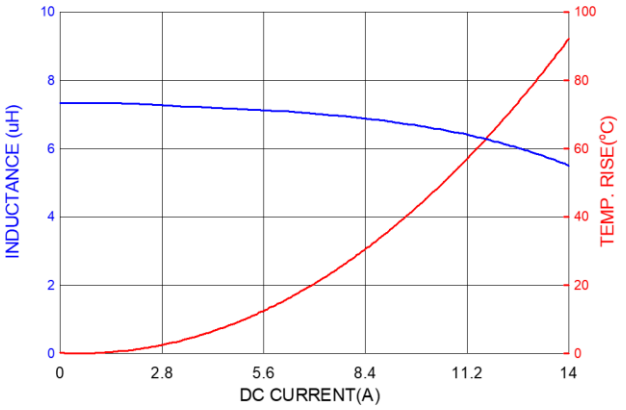


PICQ1004H6R8MF

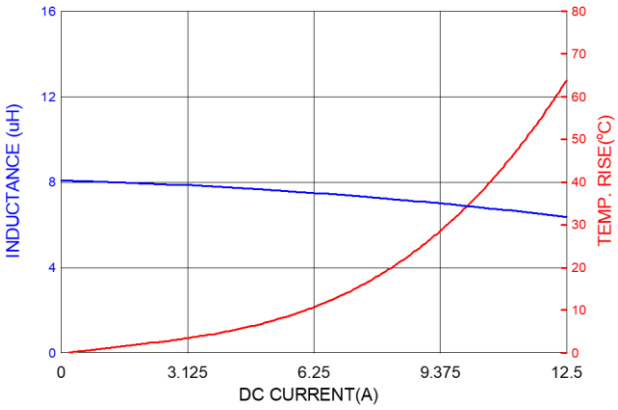


NOTE: Specifications subject to change without notice. Please check our website for latest information.

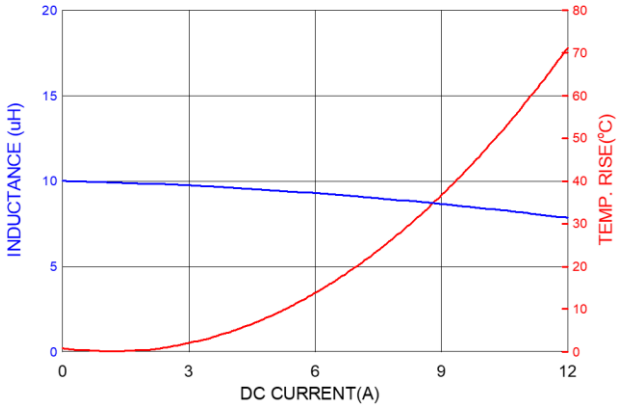
PICQ1004H7R3MF



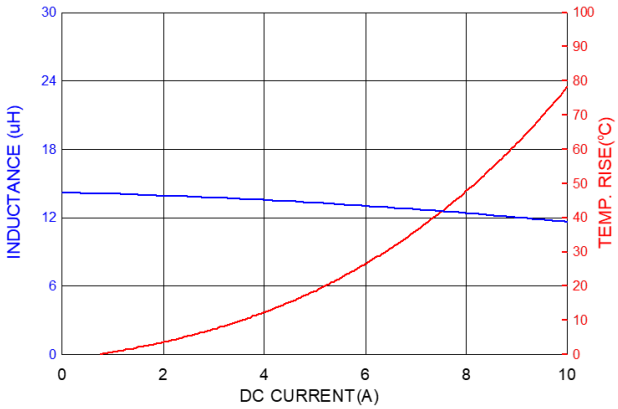
PICQ1004H8R2MF



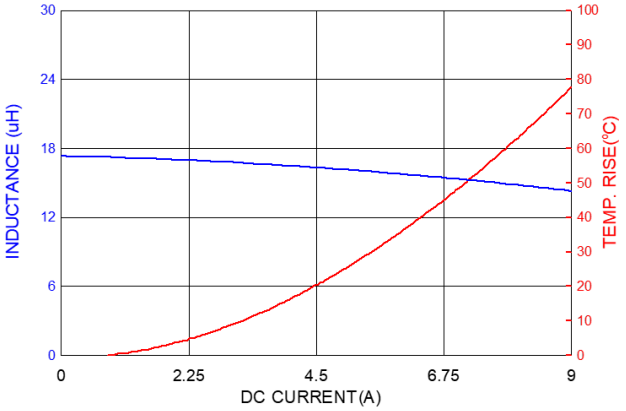
PICQ1004H100MF



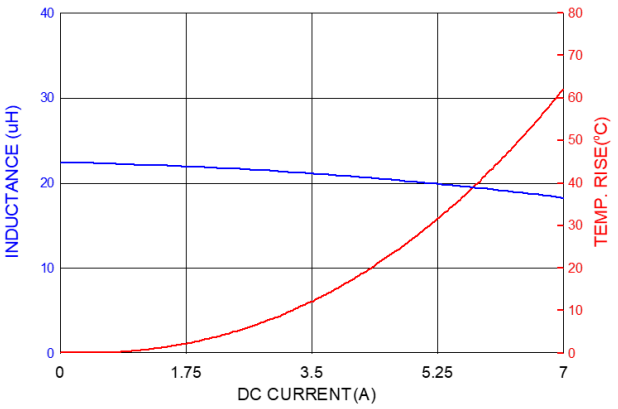
PICQ1004H150MF



PICQ1004H180MF

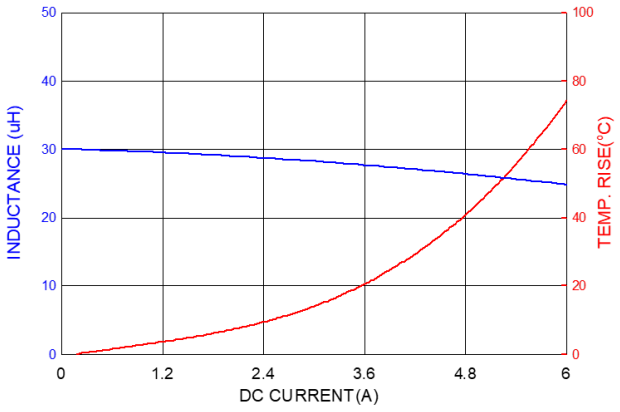


PICQ1004H220MF

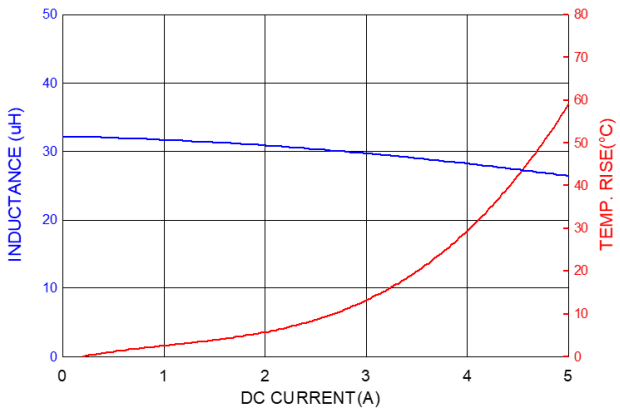


NOTE: Specifications subject to change without notice. Please check our website for latest information.

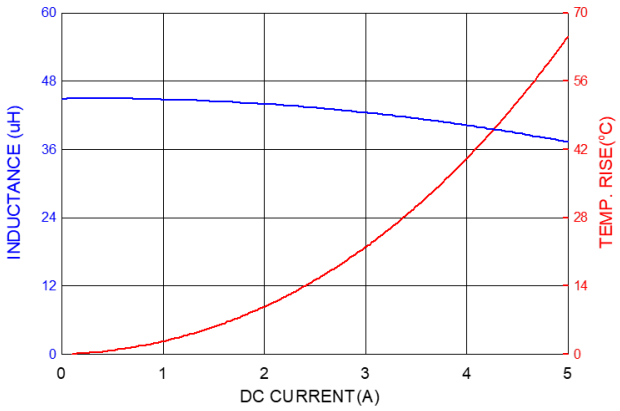
PICQ1004H270MF



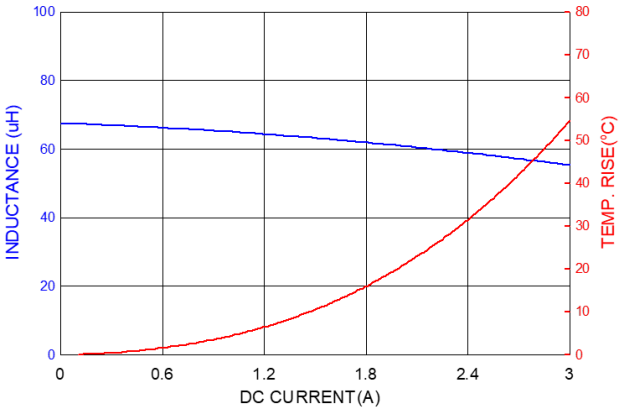
PICQ1004H330MF



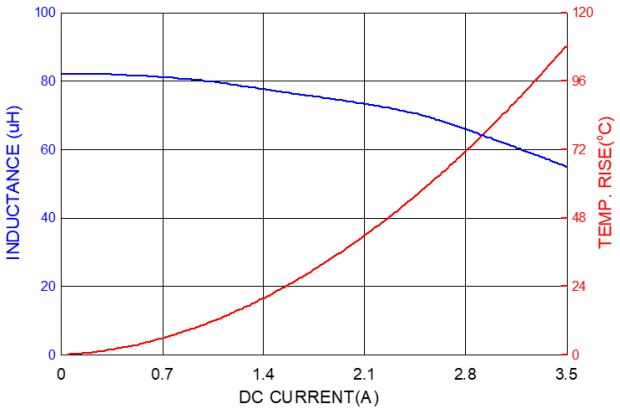
PICQ1004H470MF



PICQ1004H680MF



PICQ1004H820MF



NOTE: Specifications subject to change without notice. Please check our website for latest information.

8. Soldering Specification

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

8-1. IR Soldering Reflow

Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020E).

8-2. Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

Note:

(a) Preheat circuit and products to 150°C.

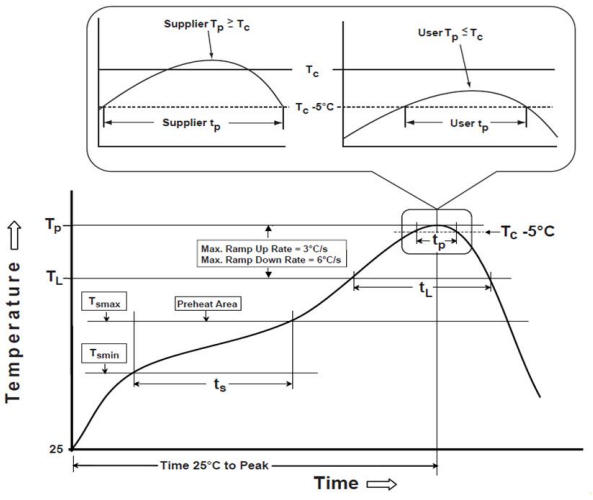
(b) 355°C tip temperature (Max.)

(c) Never contact the ceramic with the iron tip

(d) 1.0mm tip diameter (Max.)

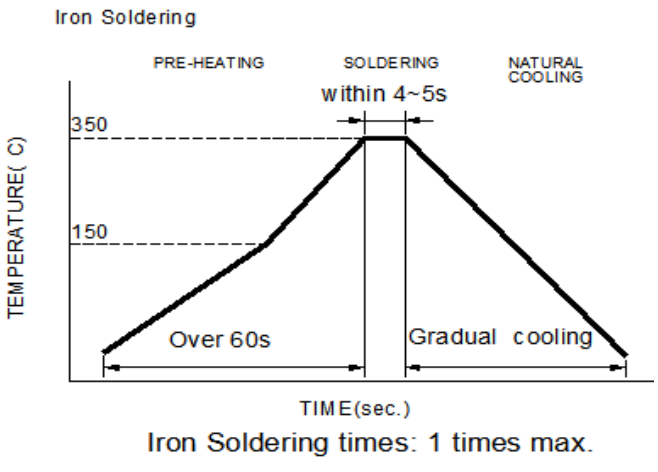
(e) Use a 20 watt soldering iron with tip diameter of 1.0mm

(f) Limit soldering time to 4~5 sec.



Reflow times: 3 times Max

Figure 1: IR Soldering Reflow



Soldering iron method: 350±5°C Max

Figure 2: Iron soldering temperature profiles

NOTE: Specifications subject to change without notice. Please check our website for latest information.

Table (1.1) Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min (T_{smin}) -Temperature Max (T_{smax}) -Time (t_s) from (T_{smin} to T_{smax})	 150°C 200°C 60-120seconds
Ramp-up rate ($T_L$to T_p)	3°C /second max.
Liquids temperature (T_L) Time (t_L) maintained above T_L	217°C 60-150 seconds
Classification temperature (T_c)	See Table (1.2)
Time (t_p) at Tc- 5°C (Tp should be equal to or less than Tc.)	*< 30 seconds
Ramp-down rate (T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

*Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

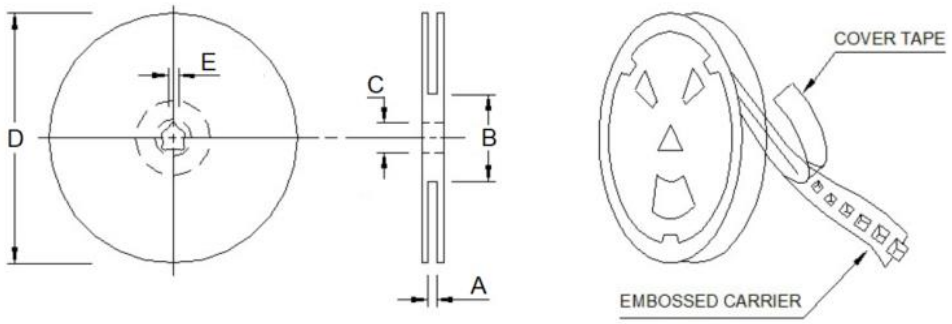
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020E.

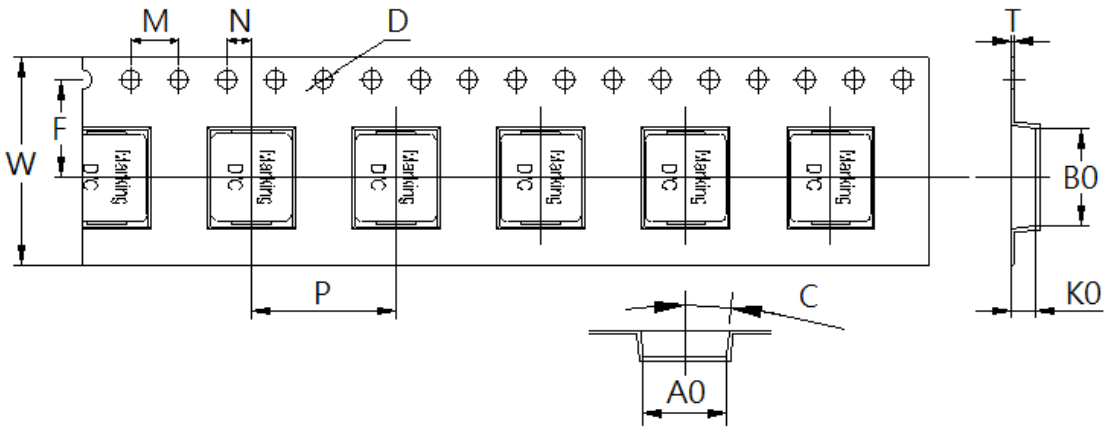
9. Packaging Information

9-1. Reel Dimension (Unit: mm)



Type	A	B	C	D	E
13”x24mm	24.4+2.0/-0.0	100.0±2.0	13.0+0.5/-0.2	330.0	2.0±0.5

9-2. Tape Dimension (Unit: mm)



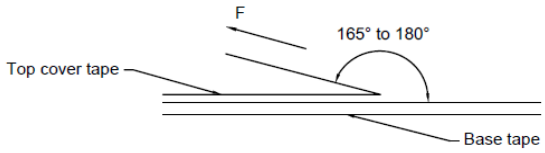
B0	A0	K0	P	W	F
11.60±0.10	10.40±0.10	4.50±0.10	16.00±0.10	24.00±0.30	11.50±0.10
T	M	N	D	C	-
0.35±0.05	4.00	2.00	1.50±0.10	3°	-

NOTE: Specifications subject to change without notice. Please check our website for latest information.

9-3. Packaging Quantity (Unit: Pcs)

Chip/ Reel	500
Inner box	1,000
Carton	4,000

9-4. Tearing Off Force



The force for tearing off cover tape is according to the follow table, in the arrow direction under the following conditions.
(Referenced ANSI/EIA-481-D-2008 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300±10

Tape Size	8 mm	12 to 56 mm	72 mm or Wider
Tearing Off Force (grams)	10~100	10~130	10~150

Application Notice

1. Storage Conditions

To maintain the solderability of terminal electrodes:

(a) Recommended products should be used within 12 months from the time of delivery.

(b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation

(a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

(b) Vacuum pick up is strongly recommended for individual components.

(c) Bulk handling should ensure that abrasion and mechanical shock are minimized.